

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1–33 (canceled)

Claim 34 (currently amended) A test circuit for testing an integrated circuit on a wafer, the test circuit formed on the wafer with the integrated circuit, the test circuit comprising:

- a) a base ring oscillator circuit;
- b) a plurality of sub-circuits coupled to the base ring oscillator circuit; and
- c) a control circuit to selectively couple the sub-circuits to the base ring oscillator circuit to produce different versions of a variable ring oscillator circuit associated with a selected sub-circuit,

wherein the test circuit conducts a separate test of the integrated circuit for ~~each sub-circuit selected by the control~~ at least one of the versions of the variable ring oscillator circuit.

Claim 35 (original) The test circuit of claim 34 wherein each test conducted by the test circuit is a parametric test.

Claim 36 (currently amended) The test circuit of claim 35 wherein the sub-circuits when coupled to the base ring oscillator circuit change the frequency of oscillation of the variable ring oscillator circuit.

Claim 37 (currently amended) The test circuit of claim 36 wherein at least one sub-circuit comprises a capacitive load to change the frequency of oscillation of the variable ring oscillator circuit.

Claim 38 (currently amended) The test circuit of claim ~~37~~36 wherein at least one sub-circuit comprises a capacitive load and a resistive load to change the frequency of oscillation of the variable ring oscillator circuit.

Claim 39 (currently amended) The test circuit of claim 38 wherein at least one sub-circuit comprises a delay element to change the frequency of oscillation of the variable ring oscillator circuit.

Claim 40 (original) The test circuit of claim 37 wherein the capacitive load comprises at least one capacitor.

Claim 41 (original) The test circuit of claim 38 wherein the capacitive load comprises at least one capacitor and the resistive load comprises at least one resistor.

Claim 42 (original) The test circuit of claim 39 wherein the delay element comprises at least one inverter.

Claim 43 (original) The test circuit of claim 42 wherein each inverter is a standard CMOS inverter.

Claim 44 (currently amended) The test circuit of claim 34 wherein the control circuit comprises a sequencer to selectively couple the sub-circuits to the variable ring oscillator circuit to produce a series of test states.

Claim 45 (original) The test circuit of claim 34 wherein the test circuit is formed on the wafer with at least two metallization layers of the integrated circuit.

Claim 46 (original) The apparatus of claim 34 wherein the test circuit is formed on the wafer with at least one metallization layer and one polysilicon layer of the integrated circuit.

Claim 47 (currently amended) The test circuit of claim 34 wherein the test circuit produces a test result signal that is the output of the variable ring oscillator circuit.

Claim 48 (currently amended) The apparatus of claim 44 wherein the test circuit further comprises an antenna adapted to receive a signal, a power supply circuit coupled to the antenna and adapted to provide power to the test circuit and a transmitter circuit coupled to the variable ring oscillator circuit and the antenna and adapted to transmit a test result signal.

Claim 49 (original) The apparatus of claim 48, wherein the power supply circuit comprises a voltage rectifier coupled to the antenna, a voltage regulator coupled to the voltage rectifier and an energy storage element coupled to the voltage regulator, wherein the power supply circuit is adapted to provide a plurality of voltage levels to the test circuit.

Claim 50 (currently amended) The apparatus of claim 48, wherein the control circuit further comprises a ~~second~~ ring oscillator adapted to provide a first clock signal, and a divider coupled to the ~~second~~ ring oscillator and the sequencer and adapted to provide a second clock signal, wherein the second clock signal is provided to the sequencer so that the sequencer can provide a series of test state signals to the variable ring oscillator circuit and plurality of sub-circuits.

Claim 51 (currently amended) The apparatus of claim 48, wherein the transmitter circuit comprises a coupler which is coupled to the variable ring oscillator and the antenna and is adapted to selectively couple the output of the variable ring oscillator circuit to the antenna for transmission of the test result signal.

Claim 52 (original) The test circuit of claim 51 wherein the coupler capacitively couples the test result signal to the antenna.

Claim 53 (original) The test circuit of claim 51 wherein the coupler modulates the impedance of the antenna to transmit the test result signal.

Claim 54 (original) The test circuit of claim 34 wherein the test circuit is formed adjacent to a die containing the integrated circuit.

Claim 55 (original) The test circuit of claim 34 wherein the test circuit is formed on a die that contains the integrated circuit.

Claim 56 (original) The test circuit of claim 34 wherein the test circuit is formed on a large percentage of dies on the wafer.

Claim 57 (original) The test circuit of claim 34 wherein the test circuit is formed on dies near the edge of the wafer.

Claims 58–70 (canceled)

Claim 71 (currently amended) The apparatus of claim 51, wherein the transmitter circuit further comprises a synchronization element to couple the variable ring oscillator circuit to the coupler.

Claim 72 (canceled)